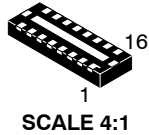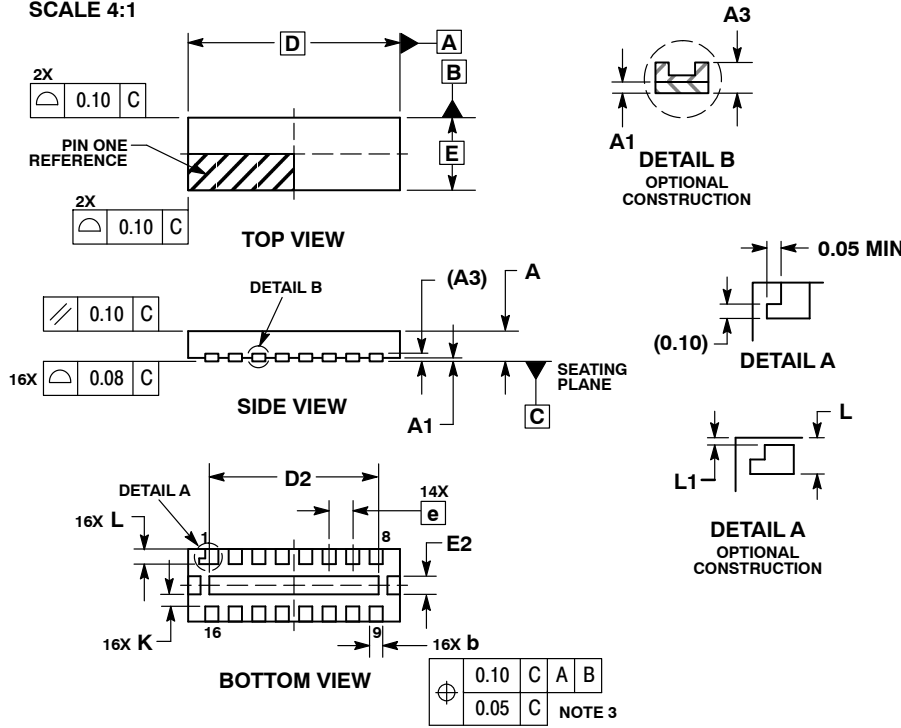**UDFN16 3.5x1.2, 0.4P**
CASE 517AF
ISSUE C

DATE 23 OCT 2012

SCALE 4:1

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

TOP VIEW

PIN ONE REFERENCE

SIDE VIEW

SEATING PLANE

BOTTOM VIEW

NOTE 3

DETAIL B
OPTIONAL CONSTRUCTION

DETAIL A

DETAIL A
OPTIONAL CONSTRUCTION

| DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.45	0.50	0.55
A1	0.00	0.03	0.05
A3		0.127 REF	
b	0.15	0.20	0.25
D		3.50 BSC	
D2	2.70	2.80	2.90
E		1.20 BSC	
E2	0.20	0.30	0.40
e		0.40 BSC	
K		0.20 TYP	
L	0.20	0.25	0.30
L1	---	---	0.10

GENERIC MARKING DIAGRAM*

XXXM
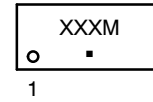
XXX = Specific Device Code
M   = Month Code
▪   = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪ ", may or may not be present.

SOLDERING FOOTPRINT*

DIMENSIONS: MILLIMETERS
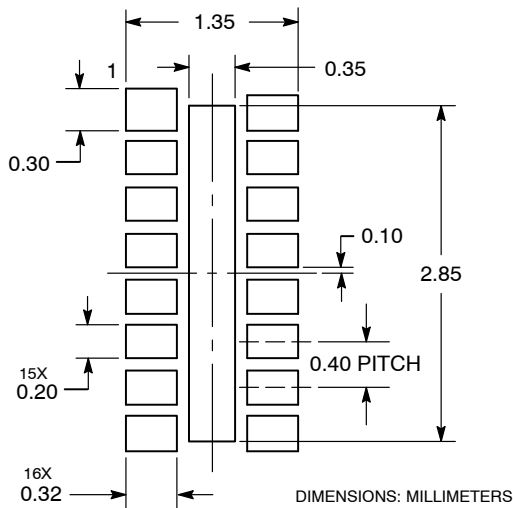
*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	UDFN16 3.5X1.2, 0.4P		PAGE 1 OF 1